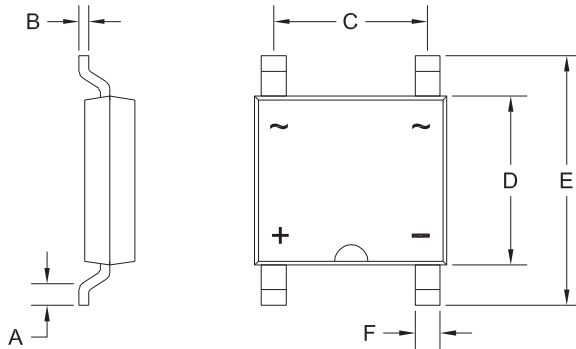


Package Details

LPDIP Case

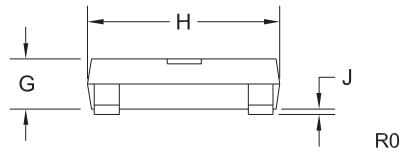


Mechanical Drawing



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.019	0.028	0.50	0.70
B	0.007	0.012	0.20	0.30
C	0.153	0.162	3.90	4.10
D	0.167	0.179	4.25	4.55
E	0.248	0.264	6.30	6.70
F	0.023	0.028	0.60	0.70
G	0.045	0.058	1.15	1.45
H	0.190	0.203	4.85	5.15
J	0.002	0.006	0.05	0.15

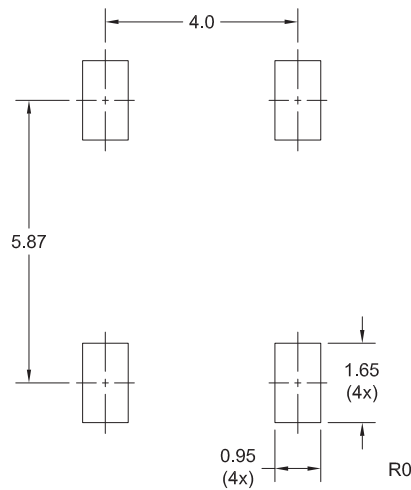
LPDIP (REV: R0)



Part Marking:

4-5 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



R0 (17-July 2012)

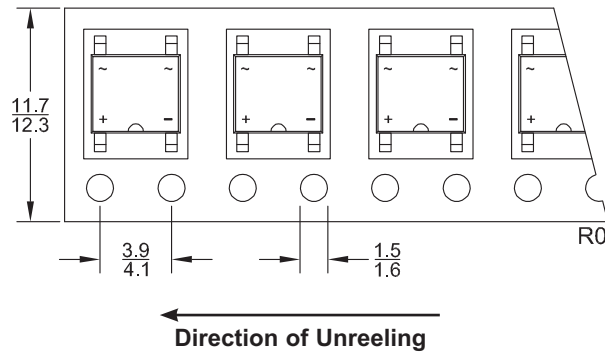
Package Details

LPDIP Case



Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 12mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

13" Reel = 4,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13"	5	20,000	15x4x15	38x10x38	8	4
	14	56,000	15x15x9	38x38x23	21	10
	26	104,000	15x15x18	38x38x46	39	18

Ordering Information

- For devices taped and reeled on 13" reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R0 (17-July 2012)

Material Composition Specification

LPDIP Case



Device average mass **89.9 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	3.23%	2.9	Si	7440-21-3	3.23%	2.9	32,258
bond wire	copper	0.42%	0.38	Cu	7440-50-8	0.42%	0.38	4,227
leadframe	Cu alloy	44.46%	39.97	Cu	7440-50-8	44.39%	39.91	443,938
				Fe	7439-89-6	0.07%	0.06	667
die attach	high temperature solder paste	2.04%	1.837	Pb	7439-92-1	1.89%	1.7	18,910
				Sn	7440-31-5	0.10%	0.091	1,012
				Ag	7440-22-4	0.05%	0.046	512
encapsulation*	EMC GREEN	49.35%	44.363	silica	60676-86-0	38%	34.16	379,978
				epoxy resin	29690-82-2	4.94%	4.44	49,388
				phenol resin	9003-35-4	4.78%	4.3	47,831
				carbon black	1333-86-4	0.15%	0.133	1,479
				metal hydroxide	1309-42-8	1.48%	1.33	14,794
plating	matte tin	0.5%	0.45	Sn	7440-31-5	0.5%	0.45	5,006

*EMC GREEN molding compound is Halogen Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (11-January 2012)